

<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  <i>(Multiple sheets used when necessary)</i>	Application No.	10/540,056
	Filing Date	June 22, 2005
	First Named Inventor	Sato et al.
	Art Unit	1795
	Examiner	John S Y Chu
SHEET 1 OF 2	Attorney Docket No.	SHIGA7.021APC

## U.S. PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
	1	7,312,014	12-25-2007	Maesawa et al.	
	2	US 2004/0033438	02-19-2004	Hamada et al.	
	3	6,949,329	09-27-2005	Endo et al.	
	4	6,630,282	10-07-2003	Oomori et al.	
	5	6,228,552	09-11-2001	Palmgren	
	6	US 2003/232273	12-18-2003	Adams et al.	
	7	US 2006/247346	11-02-2006	Hojo et al.	

## FOREIGN PATENT DOCUMENTS

Examiner Initials	Cite No.	Foreign Patent Document Country Code-Number-Kind Code Example: JP 1234567 A1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear	T <sup>1</sup>
	8	JP 2003-107707	04-09-2003	Clariant (Japan) KK		√ abstract
	9	JP 2003-075998	03-12-2003	Matsushita Elec. Inc. Co., Ltd.		√ abstract
	10	JP 2004-078153	03-11-2004	Sumitomo Chem. Co., Ltd.		√
	11	JP 2002-062655	02-28-2002	Tokyo Ohka Kogyo Co., Ltd.		√ abstract
	12	JP 2002-062656	02-28-2002	Tokyo Ohka Kogyo Co., Ltd.		√ abstract
	13	JP 2000-214587	08-04-2000	Shin Etsu Chem. Co., Ltd.		√
	14	JP H11-109631	04-23-1999	Fuji Photo Film Co., Ltd.		√
	15	WO 03/007079	01-23-2003	Wako Pure Chem. Ind., Ltd.		
	16	JP H10-142799	05-29-1998	Toshiba Corp.		√ abstract
	17	JP 2001-056558	02-27-2001	Tokyo Ohka Kogyo Co., Ltd.		√
	18	JP 2003-295444	10-15-2003	Shipley Co., LLC		√
	19	JP 2004-333549	11-25-2004	Tokyo Ohka Kogyo Co., Ltd.		√ abstract
	20	JP 2002-323768	11-08-2002	Fuji Photo Film Co., Ltd.		√

## NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>1</sup>
	21	Office Action Issued on July 1, 2008, on the Japanese Patent Application No. 2004-142581.	

Examiner Signature	Date Considered
<b>*Examiner:</b> Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

T<sup>1</sup> - Place a check mark in this area when an English language Translation is attached.

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	22	NAKAMURA et al., "Ultra Thin Film Resist for Low Energy E-beam Projection Lithography", Journal of Photopolymer Science and Technology, Vol. 15, No. 3, pp. 417-422, (2002)	
	23	YOSHIZAWA et al., "Comparative study of resolution limiting factors in electron beam lithography using the edge roughness evaluation method", Journal of Vacuum Science and Technology B, Vol. 19, Issue 6, pp. 2488-2493, (2001)	
	24	Office Action Issued on February 19, 2008, on the Japanese Patent Application No. 2003-334029.	
	25	Office Action Issued on February 19, 2008, on the Japanese Patent Application No. 2003-347136.	

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